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ENERGY BEAM CURABLE HYDROPHILIC PRESSURE SENSITIVE  
ADHESIVE COMPOSITION AND USE THEREOF

ABSTRACT

An energy beam curable hydrophilic pressure sensitive adhesive composition comprising a hydrophilic pressure sensitive adhesive (A) and an energy beam  
5 polymerizable compound (B), optionally together with a photopolymerization initiator (C) added according to necessity. Thus, a pressure sensitive adhesive composition suitable for use in a wafer surface protective sheet is provided, which enables easily  
10 removing any residual pressure sensitive adhesive by washing with water, even if a pressure sensitive adhesive remains on a wafer surface after peeling of a pressure sensitive adhesive sheet.

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This Sheet Has Been Replaced

